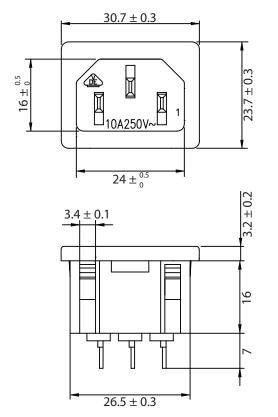
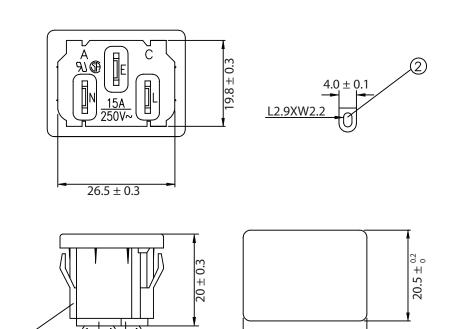
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REVISION						
REV.	DESCRIPTION	DATE	APPROVED			
В	RoHS Compliancy	06-01-06	DP			
C	Updated Dimensions	06-30-08	DP			





PANEL CUTOUT THICKNESS FOR PLASTIC PANEL 0.8mm~1.5mm PANEL CUTOUT THICKNESS FOR STEEL PANEL 0.8mm~2.0mm

 $27 \pm {0.2}_{0}$ 

## NOTES:

MATERIAL:

HOUSING: THERMOPLASTIC TERMINAL: COPPER ALLOY

RATING:

UL, CSA: 15A 250V AC VDE: 10A 250V AC

INSULATION RESISTANCE: OVER 100M OHM 500V DC DIELECTRIC RESISTANCE: 2000V AC ONE MINUTE

APPROVALS: UL,CSA,VDE ROHS COMPLIANT

## CONTROLLED

2	Termin	nal Set COPPER	ALLOY Tin-Plated				
1	Housir	ng SNAP-IN TYF	PE				
Dim range		Tolerance +/-	Qualtek Electronics Corp.  PPC DIVISION				
(mm) (mm)		(mm)	Part Number:	701W-X2/02	RoHS Compliant		
	0-1	0.15	Description:				
	1-6	0.20	AC RECEPTACLE				
	6-18	0.30			DEVIC		
1	18-50	0.50		UNIT: mm	REV. C		
5	0-120	0.70	Drawn / Date	Checked / Date	Approved / Date		
12	20-250	0.90	B.Zhang 10-25-04 JJI		JJH / 10-25-04	10-25-04	
25	50-500	1.20	10-25-04	10 25 04	33117 10 23 04		